

<p>2000-426247/37 KIZAI KK</p> <p>1998.10.30 1998-310487(+1998JP-310487) (2000.05.26) C23C 18/38, 18/18, C25D 5/54, C23C 18/32</p> <p>Method of plating non-conductors and liquid compositions for electroless deposition C2000-129683</p>	<p>A(11-C4B) M(13-B)</p>
<p><b>KIZA- 1998.10.30</b> *JP 2000144439-A</p>	<p><b>EXAMPLE</b> An ABS resin plate (thickness=3mm) was degreased, etched and rinsed, treated with the solution (1 liter) containing 100 ml of 35 % HCl and 10 ml of Cr removing agent for 1 minute, activated with catalytic solution containing Pd-Sn sol at 35 °C for 5 minutes, electroless deposited with the solution containing 10g/liter of copper sulfate, 40 g/liter of tartaric acid, 60 g/liter of lithium hydroxide, and 1 g/liter of ethylene glycol for 7 minutes, and plated. (11pp032DwgNo.0/0)</p>
<p><b>NOVELTY</b> Method comprises following three processes, a; the surface of non-conductive material is activated with the agent containing (noble metal/stannous salt) colloidal sol, b; the material is dipped into the electroless deposition solution containing one of formic acid, its salts, and alcohol as reducing agent and catalytic metal ion to give the material electric conductivity, and c; the material is electroless deposited or plated.</p> <p><b>USE</b> Used for plating non-conductors.</p> <p><b>ADVANTAGE</b> This method is able to plate non-conductors without using hazardous formaldehyde or hypo-phosphorus acid.</p>	<p>JP 2000144439-A</p>